Trenz Electronic GmbH - TE0741-02-325-2CF Datasheet

Welcome to E-XFL.COM

Understanding Embedded - Microcontroller, Microprocessor, FPGA Modules

Embedded - Microcontroller, Microprocessor, and FPGA Modules are fundamental components in modern electronic systems, offering a wide range of functionalities and capabilities. Microcontrollers are compact integrated circuits designed to execute specific control tasks within an embedded system. They typically include a processor, memory, and input/output peripherals on a single chip. Microprocessors, on the other hand, are more powerful processing units used in complex computing tasks, often requiring external memory and peripherals. FPGAs (Field Programmable Gate Arrays) are highly flexible devices that can be configured by the user to perform specific logic functions, making them invaluable in applications requiring customization and adaptability.

Applications of Embedded - Microcontroller,

Details	
Product Status	Discontinued at Digi-Key
Module/Board Type	FPGA Core
Core Processor	Kintex-7 325T
Co-Processor	-
Speed	200MHz
Flash Size	32MB
RAM Size	-
Connector Type	Samtec LSHM
Size / Dimension	1.97" x 1.57" (50mm x 40mm)
Operating Temperature	0°C ~ 70°C
Purchase URL	https://www.e-xfl.com/product-detail/trenz-electronic/te0741-02-325-2cf

Company Profile

Since 1992, Trenz Electronic GmbH successfully operates as a development service enterprise in the electronics branch. Our services include design-in support as well as turnkey design which typically cover all steps from product specification, hardware and software design up to prototyping and production.

We are particularly specialized in the design of high-speed data acquisition, high-accuracy measurement and embedded digital signal processing systems based on FPGA and ARM architectures.

We maintain long-term customer relationships, characterized by flexibility and technical competence.

Hardware Design

- System Architecture and Design
- Hardware Integration (Design-In)
- Ultrafast Digital Logic
- Analog and Mixed Signal
- Digital Signal Processing
- Schematic Capture and PCB Layout

HDL Design

- FPGA and System-On-Chip Design
- System Design and Synthesis
- HDL Design (VHDL,Verilog)
- Integration of Soft-Cores (Xilinx MicroBlaze, ARM Cortex …)
- USB, PCI-Express, Gigabit Ethernet
- Ultrafast ADC/DAC Interfaces

Software Development

- Device Driver and Application Software development
- Software and Firmware development

ISO 9001:2008 (quality management) certified

ISO 14001:2004 (environmental management) certified

Trenz Electronic GmbH

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TE0803 Series

Xilinx Zynq UltraScale+, DDR4, SPI Boot Flash, Serial transceiver

5.2 form X factor 7.6

Overview

The Trenz Electronic TE0803 is an industrial-grade MPSoC module integrating a Xilinx Zynq UltraScale+ with up to 8 GByte 64-Bit width DDR4 SDRAM, and max. 512 MByte SPI Boot Flash memory for configuration and operation, and powerful switch-mode power supplies for all on-board voltages. A large number of configurable I/O's is provided via rugged high-speed stacking connections.

All this in a compact 5.2 x 7.6 cm form factor, at the most competitive price.

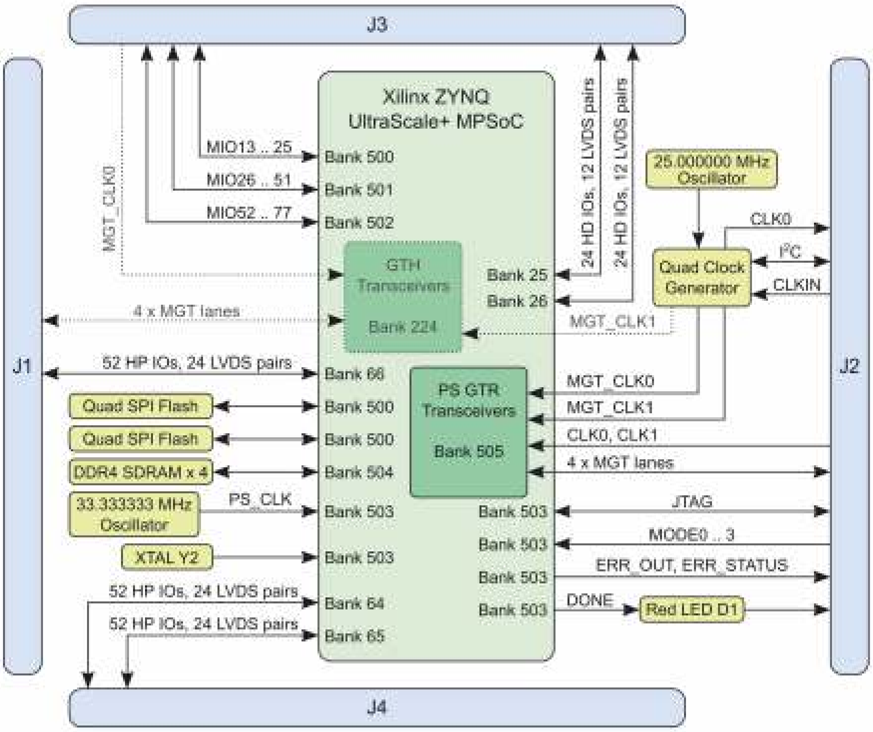
All modules produced by Trenz Electronic are developed and manufactured in Germany.

Extended device life cycle

Rugged for industrial applications

Key Features (preliminary)

- Xilinx Zynq UltraScale+ MPSoC 784 pin package (ZU3EG, optional ZU5EV)
- Memory:
  - 64-Bit DDR4 - 8 GByte max
  - SPI Boot Flash dual parallel - 512 MByte max
- B2B connectors:
  Plug-on module with 4 x 160-pin connectors
  - 65 x MIO, 156 I/O's x HP (3 banks)
  - Serial transceiver: PS GTR 4, PL GT 4 (ZU4, ZU5 only)
  - GT Reference clock input
  - PLL for GT Clocks (optional external reference)
- Size: 52 x 76 mm
- All power supplies on board.
- Other assembly options for cost or performance optimization plus high volume prices available on request.



TE0808 UltraSOM+ Series

Xilinx Zynq UltraScale+, DDR4, Flash, 20 x Transceiver

5.2 form X factor 7.6

Overview

The Trenz Electronic TE0808 is an industrial-grade MPSoC module integrating a Xilinx Zynq UltraScale+, max. 8 GByte DDR4 SDRAM with 64-Bit width, max. 512 MByte Flash memory for configuration and operation, 20 Gigabit transceivers, and powerful switch-mode power supplies for all on-board voltages. A large number of configurable I/O's is provided via rugged high-speed stacking connections.

All this in a compact 5.2 x 7.6 cm form factor, at the most competitive price.

All modules produced by Trenz Electronic are developed and manufactured in Germany

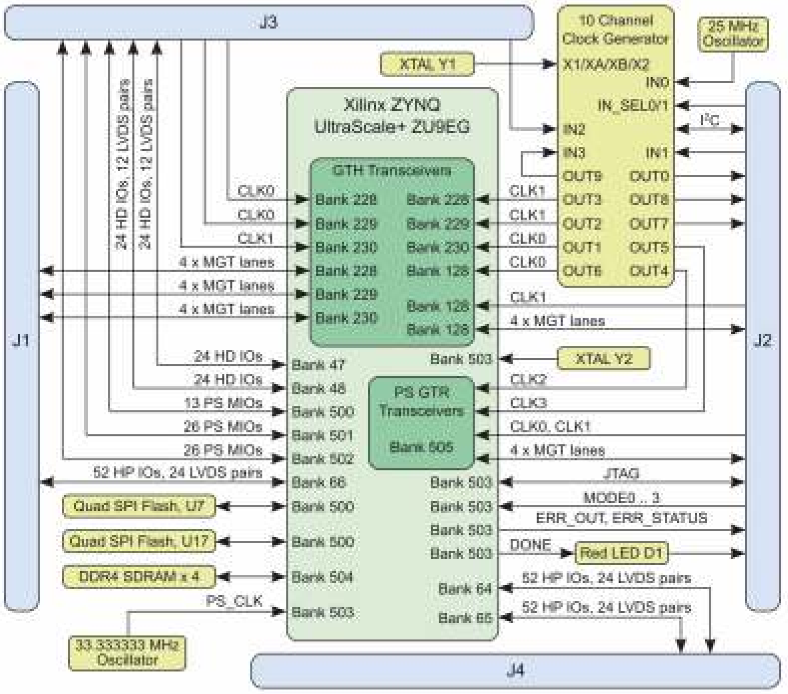
Key Features

- SoC: ZYNQ UltraScale+ ZU9EG 900 pin package
- Memory
  - 4 x 512 MByte 64-Bit DDR4 (8 GByte max.)
  - 2 x 32 MByte SPI Boot Flash dual parallel (512 MByte max.)
- User I/O
  - 65 x MIO, 48 x HD (all), 156 x HP (3 banks)
  - Serial transceiver: GTR 4 (all) + GTH 16 (all)
  - GT clocks, I2C
  - PLL clock inputs and outputs
- Size: 52 x 76 mm
- 3 mm mounting holes for skyline heat spreader
- B2B connectors: 4 x 160 pin
- Si5345 - 10 output PLL
- All power supplies on board, single 3.3V Power required
  - 14 on-board DC/DC regulators and 13 LDO's
  - LP, FP, PL separately controlled power domains
- Support for all boot modes (except NAND) and scenarios
- Support for any combination of PS connected peripherals

Other assembly options for cost or performance optimization plus high volume prices available on request.

Extended device life cycle

Rugged for industrial applications



TEC0330 Virtex-7 PCIe FMC Carrier

Overview

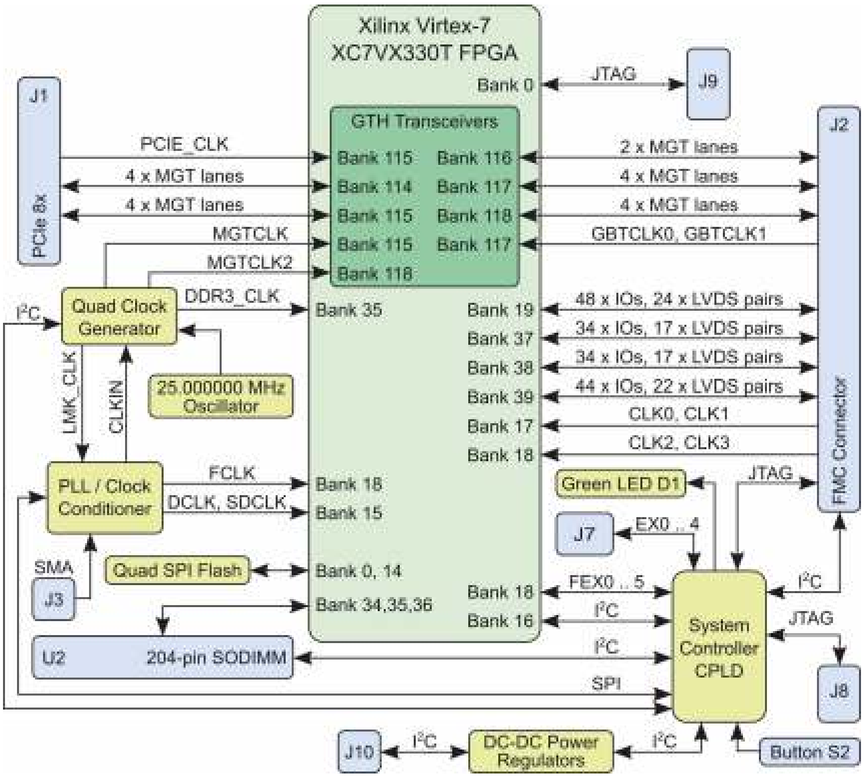
Trenz Electronic TEC0330 is an 8 lanes PCIe GEN2 Card integrating a high performance Xilinx Virtex-7 330T FPGA with 32 MByte Flash memory for configuration and operation, DDR3 SODIMM Socket and full FMC HPC connector for FPGA Mezzanine Cards.

All modules produced by Trenz Electronic are developed and manufactured in Germany.

Key Features

- FMC HPC
- 8 lane PCIe Gen 2 capable
- Xilinx Virtex-7 XC7VX330T-2FFG1157C
- DDR3 SODIMM Socket
- 32 MByte SPI Flash
- LMK04828B Clock Synthesizer
- External Clock Input

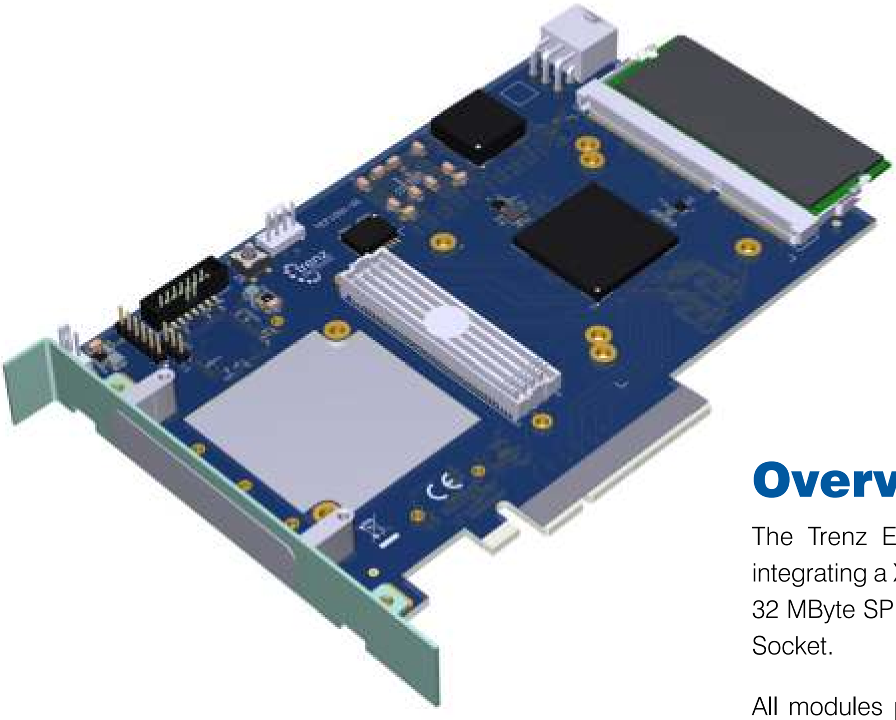
Other assembly options for cost or performance optimization plus high volume prices available on request.



www.trenz-electronic.de/tec0330

TEF1001 Series

PCIe FMC Carrier, Xilinx Kintex-7, SPI Flash, 4 lane PCIe



Overview

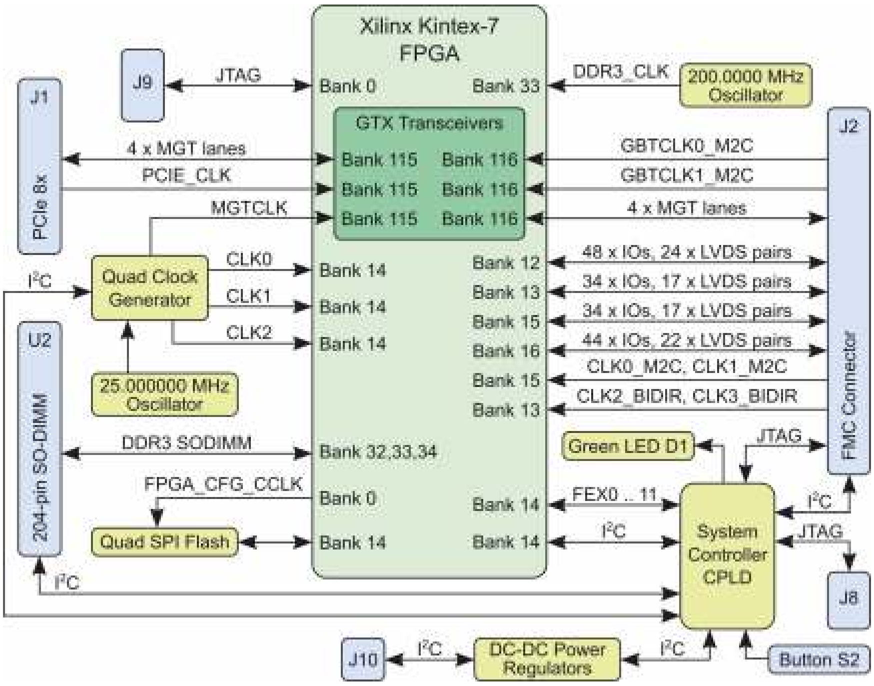
The Trenz Electronic TEF1001 is a PCIe FMC Carrier integrating a Xilinx Kintex-7 FPGA (K160T, K325T or K410T), 32 MByte SPI Flash, an 4 lane PCIe and a DDR3 SODIMM Socket.

All modules produced by Trenz Electronic are developed and manufactured in Germany.

Key Features

- One Vita 57.1 FMC HPC Slot
- 4 lane PCIe Gen 2
- Xilinx Kintex-7 XC7K160T-2FBG676I
- DDR3 SODIMM Socket
- 32 MByte SPI Flash
- Programmable clock generator Si5338
- 200 MHz Low-Jitter LVDS oscillator
- High performance DC-DC converters

Other assembly options for cost or performance optimization plus high volume prices available on request.



TE0729 Series

Xilinx Zynq, 1x Gig ETH, 512 MByte DDR3, 2x 100MBit ETH, 4 GByte eMMC, 3.3V Only

Overview

The Trenz Electronic TE0729 is an industrial-grade SoC module integrating a Xilinx Zynq-7020 with a Gigabit Ethernet transceiver, 2 x 100 MBit Ethernet, 512 MByte DDR3 SDRAM, 32 MByte Flash memory for configuration and operation, and powerful switch-mode power supplies for all on-board voltages. A large number of configurable I/O's is provided via rugged high-speed stacking strips.

All modules produced by Trenz Electronic are developed and manufactured in Germany.

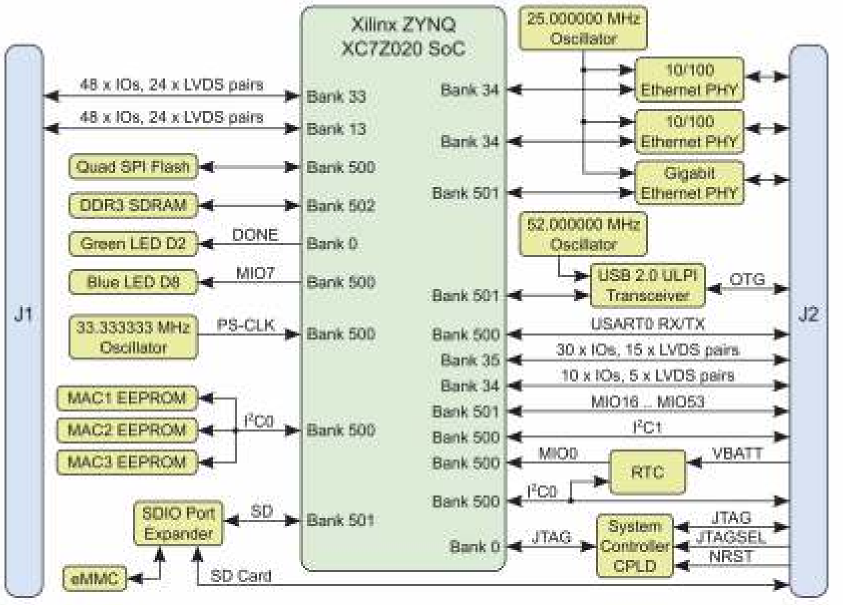
Extended device life cycle

Rugged for industrial applications

Key Features

- Zynq XC7Z020-2CLG484I
- Rugged for shock and high vibration
- 2 x ARM Cortex-A9
- 1 x 10/100/1000 Mbps Ethernet transceiver PHY
- 2 x 10/100 Mbps Ethernet transceiver PHYs
- 3 x MAC-Address EEPROMs
- 16-Bit wide 512 MByte DDR3 SDRAM
- 32 MByte QSPI-Flash-Memory
- 4 GByte e-NAND-Flash-Memory (embedded eMMC Memory)
- USB 2.0 high-speed ULPI transceiver
- Plug-on module with 2 x 120-pin high-speed hermaphroditic strips
- 136 FPGA I/O's (58 LVDS pairs possible) and 14 MIO's available on
- board-to-board connectors
- On-board high-efficiency DC-DC converters
  - 4.0 A x 1.0 V power rail
  - 1.5 A x 1.5 V power rail
  - 1.5 A x 1.8 V power rail
  - 1.5 A x 2.5 V power rail
- System management
- eFUSE bit-stream encryption
- AES bit-stream encryption
- Temperature compensated RTC (real-time clock)
- User LED
- Evenly spread supply pins for good signal integrity
- 3 mm mounting holes for Skyline heat spreader
- Cooling Solution available

Other assembly options for cost or performance optimization plus high volume prices available on request.



www.trenz-electronic.de/te0729

TE0715 Series

Xilinx Zynq, Cortex-A9, DDR3, Flash, GBit Ethernet, 4 x Transceiver

4 X 5 form factor

Key Features

- Industrial-grade Xilinx Zynq-7000 (Z-7015, Z-7030) SoM , supported by the free Xilinx Vivado WebPACK tool
- Rugged for shock and high vibration
- ARM dual-core Cortex-A9
- 10/100/1000 tri-speed gigabit Ethernet transceiver (PHY) with SGMII
  - MAC Address EEPROM
- 32-Bit-wide 1 GByte DDR3 SDRAM
- 32 MByte QSPI Flash memory (with XiP support)
- Programmable clock generator
  - Transceiver clock (default 125 MHz)
- Plug-on module with 2 × 100-pin and 1 × 60-pin high-speed hermaphroditic strips
- 132 FPGA I/O's (65 LVDS pairs possible) and 14 PS-MIO available on board-to-board connectors
- 4 GTP/GTX (high-performance transceiver) lanes GTP/GTX (high-performance transceiver) clock input
- USB 2.0 high-speed ULPI transceiver
- On-board high-efficiency DC-DC converters
  - 4.0 A x 1.0 V power rail
  - 1.5 A x 1.5 V power rail
  - 1.5 A x 1.8 V power rail
- System management
- eFUSE bit-stream encryption
- AES bit-stream encryption
- Temperature compensated RTC (real-time clock)
- User LED
- Evenly spread supply pins for good signal integrity

Other assembly options for cost or performance optimization plus high volume prices available on request.

Overview

Trenz Electronic TE0715 are industrial-grade SoC modules integrating a Xilinx Zynq-7000 SoC, a gigabit Ethernet transceiver (physical layer), 1 gigabyte DDR3 SDRAM with 32-Bit width, 32 megabyte Flash memory for configuration and operation, 4 transceivers, a USB ULPI transceiver, and powerful switch-mode power supplies for all onboard voltages. A large number of configurable I/O's is provided via rugged high-speed stacking strips. All modules in 4 x 5 cm form factor are mechanically compatible.
All this on a tiny fooprint, smaller than a credit card, at the most competitive price.

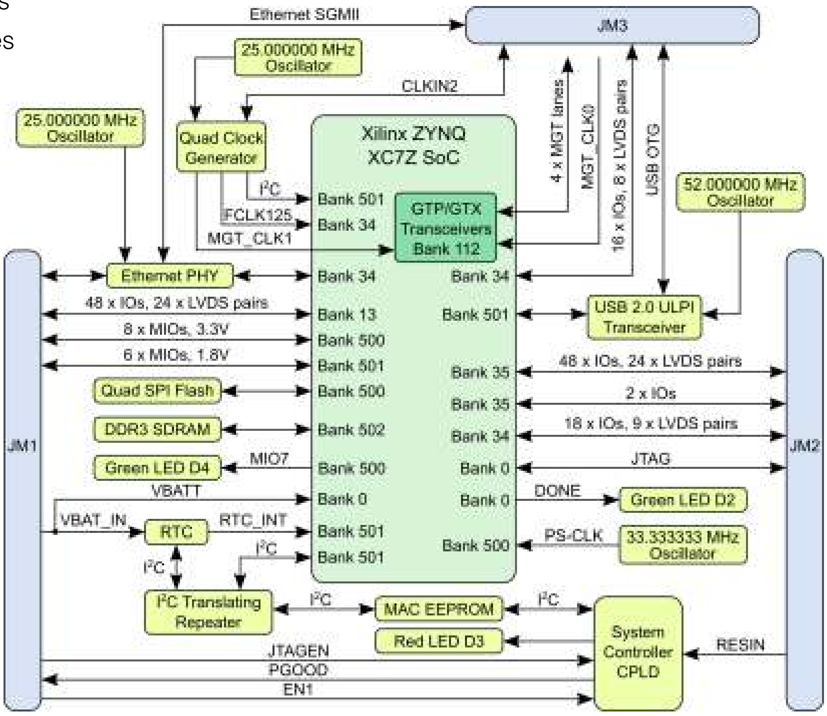
All modules produced by Trenz Electronic are developed and manufactured in Germany.

Extended device life cycle

Rugged for industrial applications

XILINX ALL PROGRAMMABLE

ZYNQ



www.trenz-electronic.de/te0715

TE0728 Series

Xilinx Zynq, 2 × Cortex-A9, DDR3, Flash, 2 × Ethernet, CAN, Automotive

Key Features

- Xilinx Zynq XA7Z020-1CLG484Q (Automotive)
- Rugged for shock and high vibration
- 2 x ARM Cortex-A9 MPCore
- 2 x 100 MBit Ethernet transceiver (PHY)
- 16-Bit-wide 512 MByte DDR3 SDRAM
- 16 MByte QSPI Flash memory (with XiP support)
- Plug-on module with 3 x 80-pin high-reliability high-speed strips
- 76 single ended I/O, 24 LVDS pairs (48 I/O) and 42 MIO available on
- board-to-board connectors
- Board-to-board connectors
- CAN transceiver (PHY)
- Temperature compensated RTC (real-time clock)
- 12 V power supply with watchdog
- On-board high-efficiency DC-DC converters
- System management and power sequencir
- eFUSE bit-stream encryption
- AES bit-stream encryption
- 3 user LEDs
- Evenly spread supply pins for good signal integrity

Other assembly options for cost or performance optimization plus high volume prices available on request.

Overview

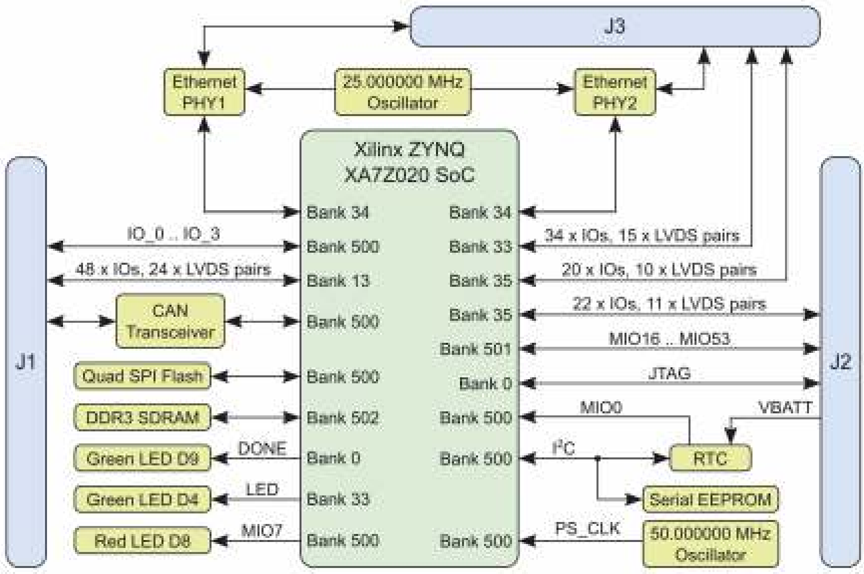
The Trenz Electronic TE0728-04-1Q is a SoC module integrating a Xilinx Automotive Zynq-7020, 512 MByte DDR3 SDRAM with 16-Bit width, 16 MByte Flash Memory for configuration and operation, two 100 Megabit Ethernet transceivers, and powerful switch-mode power supplies for all on-board voltages. A large number of con?gurable I/O's is provided via rugged high-speed stacking strips.

Within the complete module only Automotive components are installed. All this in a compact 6 x 6 cm form factor, at the most competitive price.

All modules produced by Trenz Electronic are developed and manufactured in Germany.

Extended device life cycle

Rugged for automotive applications



TE0782 Series

Xilinx Zynq, 2 × Cortex-A9, DDR3, Flash, 2 × GBit Ethernet, 2 × USB, 16 × Transceiver

8.5 form X factor 8.5

Overview

The Trenz Electronic TE0782 are industrial-grade SoC modules integrating a Xilinx Zynq-7 XC7Z035, XC7Z045 or XC7Z100, 1 GByte DDR3 SDRAM, 4 GByte eMMC, 16 GTX high-performance transceiver lanes, 32 MByte QSPI Flash memory for configuration and operation, and powerful switch-mode power supplies for all on-board voltages.

A large number of configurable I/O's is provided via rugged high-speed stacking strips. All this in a 8.5 x 8.5 cm form factor at the most competitive price.

All modules produced by Trenz Electronic are developed and manufactured in Germany.

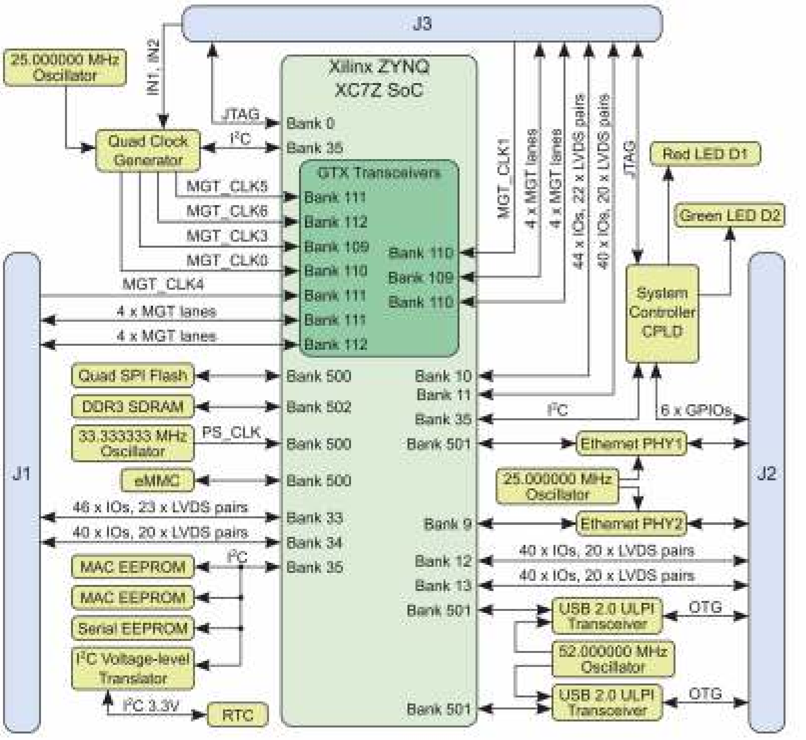
Extended device life cycle

Rugged for industrial applications

Key Features

- Industrial-grade Xilinx Zynq-7 XC7Z035, XC7Z045 or XC7Z100 SOM
- Rugged for shock and high vibration
- Dual ARM Cortex-A9 MPCore
- Real Time Clock
- 2 x Hi-Speed USB2.0 ULPI Transceiver PHY
- 2 x Gigabit Ethernet Transceiver PHY
- 2 x Ethernet MAC Address EEPROM
- 1 GByte DDR3 SDRAM
- 32 MByte QSPI Flash memory
- 4 GByte eMMC (optional up to 64 GByte)
- Optional 2 x 8 MByte HyperRAM (max 2 x 32 MByte HyperRAM)
- Si5338 PLL for GTX clocking
- Plug-on module with 3 x 160-pin high-speed strips
- 16 GTX high-performance tranceiver lanes , GTX high-performance
- Transceiver clock input
- 254 FPGA I/O's (125 LVDS pairs possible) available on board-to-board connectors
- On-board high-efficiency DC-DC converters
- System management and power sequencing
- eFUSE bit-stream encryption
- AES bit-stream encryption
- Evenly spread supply pins for good signal integrity

Other assembly options for cost or performance optimization plus high volume prices available on request.



trenz electronic

TE0726 Series

Xilinx Zynq, 512 MByte DDR3L SDRAM, 16 MByte Flash, 100 MBit Ethernet RJ45

Raspberry Pi form X factor Model 2

Overview

The Trenz Electronic TE0726 is a Rasberry Pi compatible FPGA module integrating a Xilinx Zynq-7010, 512 MByte DDR3L SDRAM, 4 USB ports, an Ethernet port and 16 MByte Flash memory for configuration und operation.

All modules produced by Trenz Electronic are developed and manufactured in Germany.

Extended device life cycle

"Ideal for Maker"
Make:

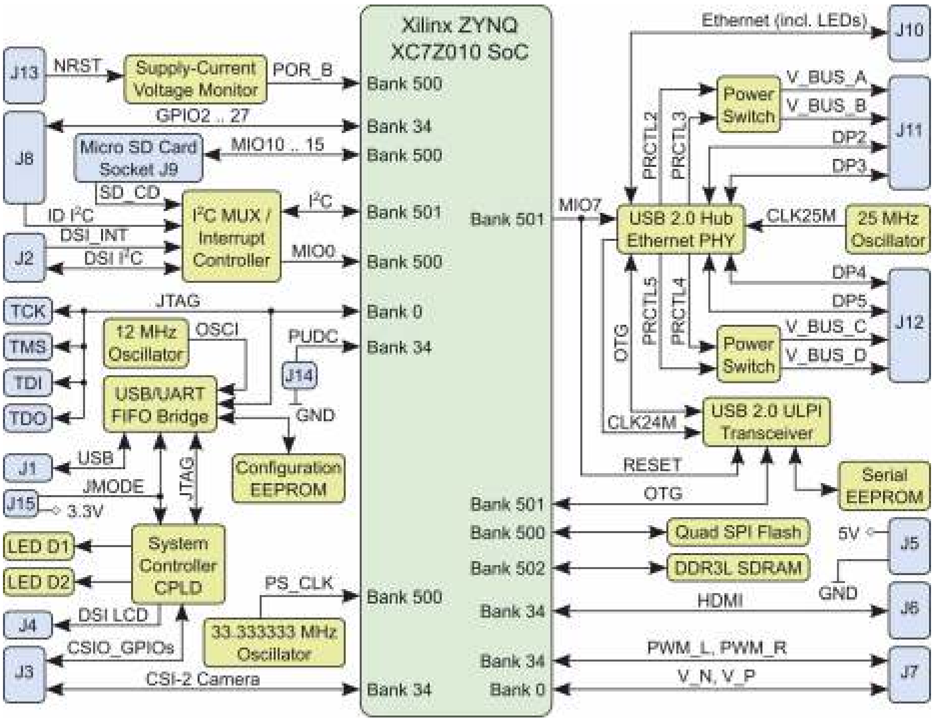
XILINX
ALL PROGRAMMABLE™

ZYNQ™

Key Features

- Xilinx Zynq XC7Z010-1CLG225C
  - 512 MByte DDR3L SDRAM
  - 16 MByte Flash
- LAN9514 USB Hub with Ethernet
  - 4 x USB with power switches
  - 100 MBit Ethernet RJ45
- Micro SD card slot
- HDMI Typ A
- DSI Connector (Display)
- CSI-2 Connector (Camera)
- Micro USB
  - power input
  - USB UART
  - JTAG ARM- und FPGA-Debug
- 3.5 mm audio plug (PWM Audio output only)
- Raspberry Pi Model 2 form faktor
- HAT header with 26 I/O's

Other assembly options for cost or performance optimization plus high volume prices available on request.



TE0711 Series

Xilinx Artix-7 T, Flash, USB, high pin count, low cost

Overview

Trenz Electronic TE0711 are industrial-grade FPGA modules integrating a Xilinx Artix-7 T FPGA, 32 MByte Flash memory for configuration and operation, and powerful switch-mode power supplies for all on-number of board voltages. A large configurable I/O's is provided via rugged high-speed stacking strips. All modules in 4 x 5 cm form factor are mechanically compatible.

All this on a tiny footprint, smaller than a credit card, at the most competitive price.

All modules produced by Trenz Electronic are developed and manufactured in Germany.

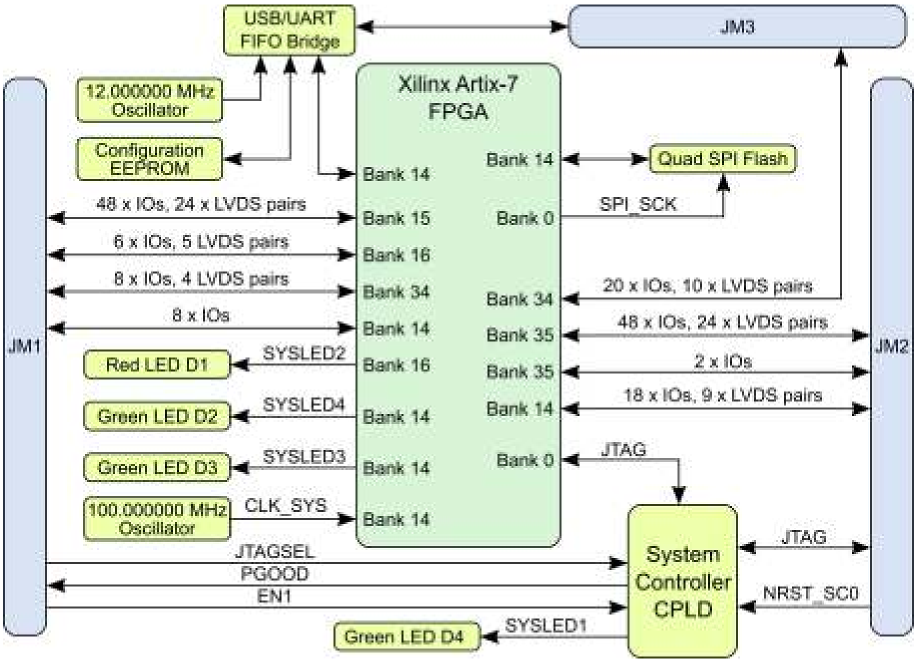
Key Features

- Industrial-grade Xilinx Artix-7 (15T to 100T) SoM, supported by the free Xilinx Vivado WebPACK tool
- Rugged for shock and high vibration
- 32 MByte QSPI Flash memory (with XiP support)
- 100 MHz programmable MEMS oscillator
- Plug-on module with 2 × 100-pin and 1 × 60-pin high-speed hermaphroditic strips
- 178 FPGA I/O's (84 differential pairs) available on board-to-board connectors
- On-board high-efficiency DC-DC converters
  - 4.0 A x 1.0 V power rail
  - 1.0 A x 1.8 V power rail
- System management and power sequencing
- eFUSE bit-stream encryption
- AES bit-stream encryption
- 3 user LEDs
- FTDI USB to UART/FIFO bridge
- Evenly-spread supply pins for good signal integrity

Other assembly options for cost or performance optimization plus high volume prices available on request.

Extended device life cycle

Rugged for industrial applications



www.trenz-electronic.de/te0711

TE0712 Series

Xilinx Artix-7 T, DDR3, Flash, 100 MBit Ethernet, 4 x Transceiver, High pin count

Overview

Trenz Electronic TE0712 are industrial-grade FPGA modules integrating a Xilinx Artix-7 T FPGA, a Megabit Ethernet transceiver (physical layer), 1 Gigabyte DDR3 SDRAM with 32-Bit width, 32 Megabyte Flash memory for configuration and operation, and powerful switch-mode power supplies for all on-board voltages. A large number of configurable I/O‘s is provided via rugged high-speed stacking strips. All modules in 4 x 5 cm form factor are mechanically compatible.
All this on a tiny footprint, smaller than a credit card, at the most competitive price.

All modules produced by Trenz Electronic are developed and manufactured in Germany.

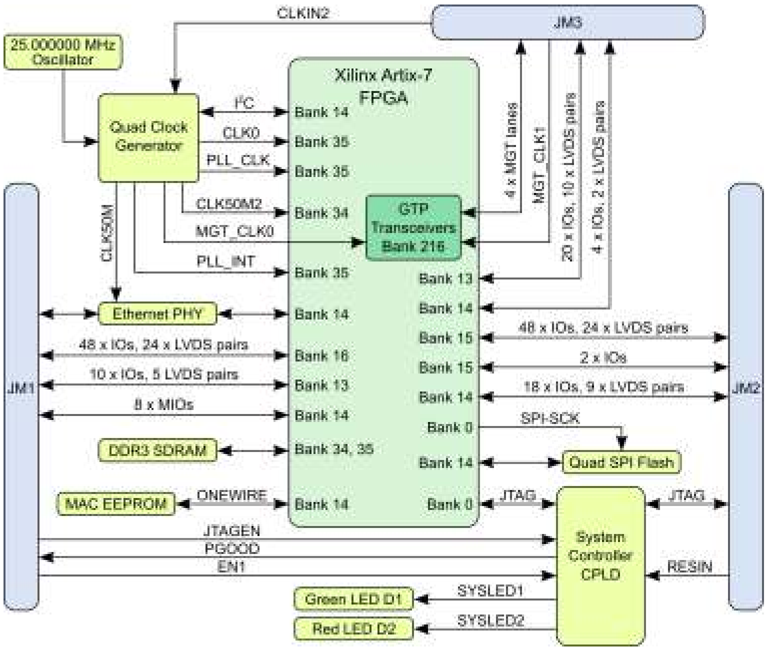
Extended device life cycle

Rugged for industrial applications

Key Features

- Industrial-grade Xilinx Artix-7 (15T to 200T) SoM, supported by the free Xilinx Vivado WebPACK tool
- Rugged for shock and high vibration
- 1 GByte DDR3 SDRAM
- 100 MBit Ethernet PHY
  - MAC Address EEPROM
- 32 MByte QSPI Flash memory (with XiP support)
- Programmable clock generator
  - Transceiver clock (default 125 MHz)
  - Fabric clock (default 200 MHz)
- Plug-on module with 2 × 100-pin and 1 × 60-pin high-speed hermaphroditic strips
- 158 FPGA I/O‘s (78 differential pairs) available on board-to-board connectors
- 4 GTP (high-performance transceiver) lanes
  - GTP (high-performance transceiver) clock input
- On-board high-efficiency DC-DC converters
  - 12 A x 1.0 V power rail
  - 1.5 A x 1.8 V power rail
  - 1.5 A x 1.5 V power rail
- System management and power sequencing
- eFUSE bit-stream encryption
- AES bit-stream encryption
- User LED
- Evenly spread supply pins for good signal integrity

Other assembly options for cost or performance optimization plus high volume prices available on request.



www.trenz-electronic.de/te0712

TE0713 Series

Xilinx Artix-7 T, DDR3L, USB 3.0, 4 GTP lanes

Overview

The Trenz Electronic TE0713 is an industrial-grade FPGA module integrating a Xilinx Artix-7 FPGA, USB 3.0 to FIFO bridge, 1 GByte of DDR3L SDRAM, 32 MByte Flash memory for configuration and operation, and powerful switching-mode power supplies for all on-board voltages. Numerous configurable I/O's are provided via rugged high-speed strips. Modules in 4 x 5 cm form factor are fully mechanically and largely electrically compatible among them. All this on a tiny footprint, smaller than a credit card, at the most competitive price.

All modules produced by Trenz Electronic are developed and manufactured in Germany.

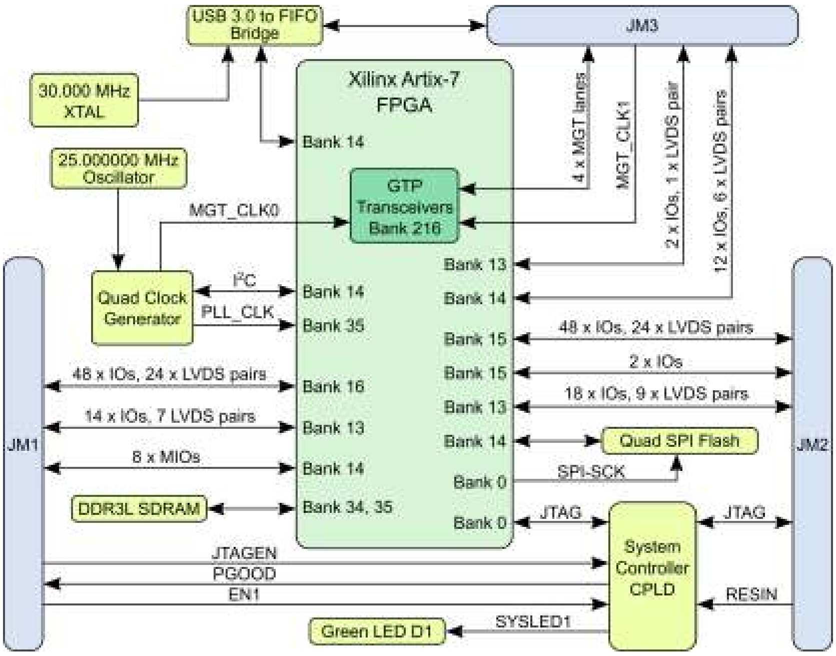
Extended device life cycle

Rugged for industrial applications

Key Features

- Xilinx Artix-7 (15T to 200T) SoM
- Both industrial and commercial temperature ranges available
- Rugged for high shock and high vibration resistance
- 1 GByte DDR3L 32-bit SDRAM
- 32 MByte QSPI Flash memory (with XiP support)
- USB 3.0 to FIFO interface bridge
- Programmable clock quad generator
  - GTP transceiver clock (default 125 MHz)
  - Fabric clock (default 200 MHz)
- Plug-on module with 2 x 100-pin and 1 x 60-pin high-speed hermaphroditic strips
- 152 FPGA I/O's (75 differential pairs) available via B2B connectors
- 4 GTP (multi Gigabit transceiver) lanes
- External clock input for GTP transceivers via B2B connector
- On-board high-efficiency DC-DC converters
- System management and power sequencing
- eFUSE bit-stream encryption
- AES bit-stream encryption
- User configurable LED
- Evenly spread supply pins for good signal integrity.

Other assembly options for cost or performance optimization plus high volume prices available on request.



www.trenz-electronic.de/te0713

TE0790 / TE0790-L

Xmod Form-Factor, FT2232H, Lattice XO2-256 CPLD, 4 Position DIP Switch

Overview

Xmod-USB-X is a universal USB adapter with 2 channels based on FTDI FT2232H USB2 HS Interface chip.

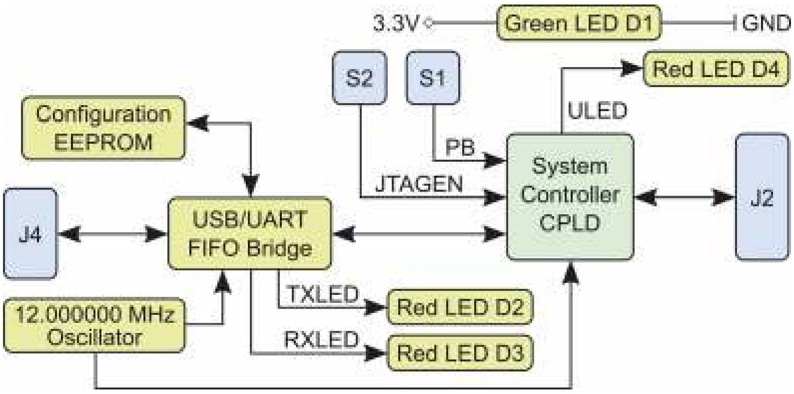
In the consigned default configu-ration Port A is JTAG and Port B is a serial interface. FT2232H port A and B are connected to small on-board programmable CPLD to allow flexible application specific remappings of FT2232H functions into 8 user I/O pins of single Xmod 12 x 8 Module.

Minimum PCB area on base board to support JTAG function 5 x 10 mm (does not include mounting hole space).
TE0790 is compatible with Xilinx Tools in contrast to the TE0790-01L, that can be used flexibly.

All modules produced by Trenz Electronic are developed and manufactured in Germany.

Key Features

- Xmod form-factor
  - Supported base slots: 6 x 2, 8 x 4, 10 x 6, 12 x 8, 5 x 2, 5 x 3
  - Size: 20 x 25 mm
  - M3 mounting hole
- FT2232H
  - Channel B RX/TX LED's (on top, not visible from front)
  - Mini-USB connector (more rugged then micro-USB)
  - 93C56 EEPROM
- Lattice XO2-256 CPLD
  - On board programmable using Lattice tools
  - 8 universal I/O pins
  - VCCIO either 3.3 V or user supplied (1.8 to 3.3V)
  - Red user LED (front visible)
  - 12 MHz clock from on-board Oscillator
- LDO for optional USB power
- Green Power-on LED (front visible)
- User button (front accesible)
- 4 position DIP switch
  - Choose CPLD program mode
  - FTDI EEPROM disable (not implemented in PCB REV 1)
  - Use VIO same as VCC
  - Use VCC from USB



TE Carrier Boards
built for Trenz Electronic micromodules with 4 x 5 cm form factor

The Trenz Electronic Carrier Boards are base-boards for 4 x 5 SoMs, which exposes the modules B2B-connector-pins to accessible connectors and provides a whole range of on-board components to test and evaluate Trenz Electronic 4 x 5 SoMs.

TE0701

- Overvoltage-, undervoltage- and reversed- supply-voltage-protection
- Barrel jack for 12 V power supply
- Carrier Board System-Controller CPLD
- Mini CameraLink connector
- RJ45 Gigabit Ethernet MagJack
- FPGA Mezzanine Card (FMC) connector
- USB JTAG- and UART interface with Mini-USB connector
- HDMI transmitter with HDMI connector
- 8 x user LED's, 2 x user push buttons, 2 x DIP switch
- PMOD connectors, Micro SD card socket and Micro-USB interface

TE0703

- 2 x VG96 backplane connectors (mounting holes and solder pads)
- SDIO port expander with voltage-level translation
- Micro SD card socket
- 4 x user LED's, 1 x user-push button, 2 x user configurable DIP switches
- Mini USB connector (USB JTAG and UART interface)
- RJ45 Gigabit Ethernet socket with 4 integrated LED's.
- USB host connector
- Barrel jack for 5 V power supply input
- DC-DC step-down converter for 3.3 V power supply
- USB JTAG and UART interface

TE0705

TE0705 is a "downgraded" version of TE0701. As little as possible has been changed in functionality except the functionality that was removed.

Changes from TE0701

- PMOD connectors changed to IDC headers
- HDMI removed
- CL connector removed
- USB connector position changed
- 5 pin header support added on both USB interfaces
- 12 V DC power input connector changed to different type
- FMC connector removed and replaced by two dual row 100 mil pin headers

TE0706

- VG96 backplane connector and 50-pin IDC male connector socket
- SDIO port expander with voltage-level translation
- Micro SD card socket and a USB type A connector
- 1 x user push button, user configurable DIP switch
- 1 x RJ45 Gigabit Ethernet MagJack
- 1 x Ethernet PHY
- Barrel jack for 5 V power supply input
- DC-DC step- down converter for 3.3 V power supply
- JTAG pins on 12-pin header
- 3 x VCCIO selection jumper

TEBA0841

Mainly for the use with TE0841 and TE0741 modules.

- XMOD (TE0790) pin header
- SFP connector
- Micro USB
- 1 x pin header 16 pol. (JTAG, MGT-CLK, boot mode, RST, IOs)
- 1 x pin header 10 pol. (SD IOs)
- 2 x pin headers 50 pol. (FPGA bank IOs and power)
- 1 x pin header for FPGA bank power VCCIOA and 1 x for VCCIOD
- LDO voltage regulator 3.3 V to 2.5 V
- 2 x user LED's (Red/Green)

www.trenz-electronic.de/te-baseboards

TE Carrier Boards

custom built for specific Trenz Electronic micromodules

Following Trenz Electronic Carrier Boards are custom-built base boards for specific Trenz Electronic SoMs, which exposes the module's B2B-connector-pins to accessible connectors and provides a whole range of on-board components to test and evaluate Trenz Electronic SoMs.

TEBF0808

- Mini-ITX form factor
- ATX power supply connector (Important 12 V only supply required)
- optional 12 V standard power plug
- USB 3.0 with USB 3.0 HUB
- Gigabit Ethernet RJ45
- MicroSD Card (bootable) and eMMC (bootable)
- PCIe slot - one PCIe lane (16 Lane connector)
- Displayport Single Lane
- One SATA Connector
- Dual SFP+
- FMC HPC slot (1.8 V max VCCIO)
- Fan connectors, PC enclosure, FMC fan
- Intel front panel- and HDA audio-connector
- CAN FD transceiver (10 pin IDC connector)
- 20 pins ARM JTAG connector (PS JTAG0)
- One Samtec FireFly (4 GT lanes bidir)
- One Samtec FireFly connector for reverse loopback

TEB0728

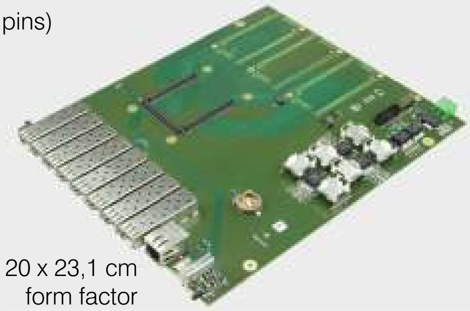
- Trenz TE0728 module socket (3 x Samtec SEM connectors 80 pins)
- 2 x RJ45 Ethernet
- SD card slot
- Power supply with DC jack
- 3 x user LED's (red/yellow/green)
- User push button

TEB0729

- Trenz TE0729 module socket (2 x Samtec BTE/BSE connectors 120 pins)
- 5 V board supply via DC jack
- 3 x RJ45 Ethernet
- 1 x MicroUSB and 1 x SD card connector
- 1 x 128K I2C CMOS Serial EEPROM
- 1 x 2K I2C Serial EEPROM
- XMOD (TE0790) pin header
- 2 x pin header FPGA bank power supply
- 1 x VBat pin header and 2 x VG96 pin header
- 1 x user push button, 1 x LED (red), user switch FPGA boot mode

TEB0745

- Trenz TE0745 module socket (3 x Samtec ST5 connectors 160 pins)
- 24 V power supply over ARKZ950/2 connecting terminal
- XMOD (TE0790) Pin Header (JTAG / UART)
- 1 x EMI Network Filter
- microSD connector
- RJ45 Ethernet connector
- USB Host connector
- 8 x SFP connector
- 6 x pin header 50 pol. (FPGA bank I/O's and power)
- 6 x pin header 12 pol. (FPGA bank I/O's and power)



20 x 23,1 cm
form factor

TEBA0714

- Trenz TE0714 module socket (2 x Samtec LSHM connectors 100 pins)
- XMOD (TE0790) pin header
- 1 x pin header 16 pol. (JTAG, MGT-CLK, boot mode, XADC, I/O's)
- 1 x pin header 10 pol. (I/O's)
- SFP connector
- LDO voltage regulator 3.3 V to 2.5 V
- 2 x user LED's (red/green) and 1 x LED (red)
- 2 x pin headers 50 pol. (FPGA bank I/O's and power)
- 1 x pin header for FPGA bank power VCCIO34 (1.8 VOUT, 2.5 V, 3.3 VOUT)
- 1 x pin header for FPGA bank power V_CFG (1.8 VOUT, 2.5 V, 3.3 VOUT)

www.trenz-electronic.de/te-baseboards

EMC²-DP

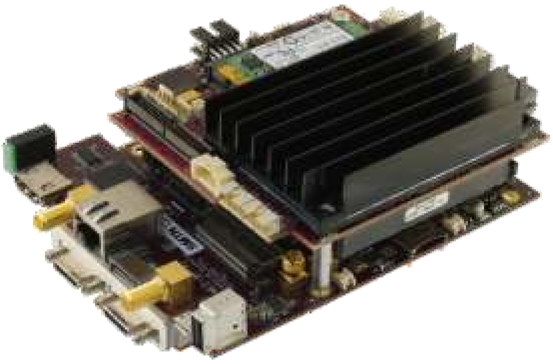
PC/104 OneBank Carrier for SoC Modules

www.sundance.technology/emc2-dp/

Providing the base for all of our PC/104 integrated systems the EMC²-DP is a PCIe/104 OneBank® Carrier for a Trenz compatible SoC Module and also has expansion for a VITA57.1 FMC™ LPC I/O board. It has I/O pins, using a 100-way Samtec RazorBeam connector system. The add-on board, called "Sundance External Interface Connector – SEIC" contains LEDs, RS232, USB2.0, HDMI, 1Gb Ethernet and SATA . The SEIC can be customized for individual applications with bespoke connectors.

The PCIe/104 OneBank® design enables the EMC²-DP to be added to robust and rugged installations for various commercial, medical, industrial and military uses.

- PCIe/104 OneBank® Carrier for Trenz SoC Modules
- PCI Express Gen 2 compatible and integrated PCI Express switch
- A number of EMC²-DP can be stacked for large I/O solutions
- Expandable with any VITA57.1 FMC I/O Module for more flexibility
- 96mm x 90 mm PC/104 Form-Factor with cable-less break-out PCB connector



oi110 - DUAL CAMERALINK

www.sundance.technology/oi110/

A dual lane CameraLink camera interface card (SMT-FMC521) and the EMC²-DP.
The integrated Xilinx FPGA allows any CameraLink format to connected to the oi110. Additional SATA-3 expansions allow connection to large storage for future processing.

- Dual CameraLink Ports
- Dual Single SATA-3 Ports
- PoCL (Power over Camera Link) support
- Up to 85MHz data rate
- Dual Base, Single Medium Base
- Single Extended Full CL Base

oi115 - HDMI IN / OUT

www.sundance.technology/oi115/

An HDMI in/out module and the EMC²-DP. As such this system gives you HDMI in and out on a one bank PC/104 FPGA carrier card.

- HDMI input/output FMC module (FMC-IMAGEON)
- HDMI input
- HDMI output
- Interface for ON Semiconductor VITA image sensor modules
- Video clock synthesizer

Xilinx development boards and kits provide an out-of-the box design solution to accelerate development time and time-to-market. Xilinx offers kits complete with evaluation boards, the Vivado Design Suite tools, IP cores, reference designs and FPGA Mezzanine Card (FMC) support – so application development begins immediately out of the box.

The Vivado Design Suite delivers a SoC-strength, IP-centric and system-centric, next generation development environment that has been built from the ground up to address the productivity bottlenecks in system-level integration and implementation.

Xilinx Zynq UltraScale+ MPSoC ZCU102 Evaluation Kit

The ZCU102 Evaluation Kit enables designers to jumpstart designs for Automotive, Industrial, Video and Communications applications. This kit features a Zynq UltraScale+ ™ MPSoC device with a quad-core ARM® Cortex-A53, dual-core Cortex-R5 real-time processors, and a Mali-400 MP2 graphics processing unit based on Xilinx's 16nm FinFET+ programmable logic fabric. The ZCU102 supports all major peripherals and interfaces enabling development for a wide range of applications.

Key Features & Benefits

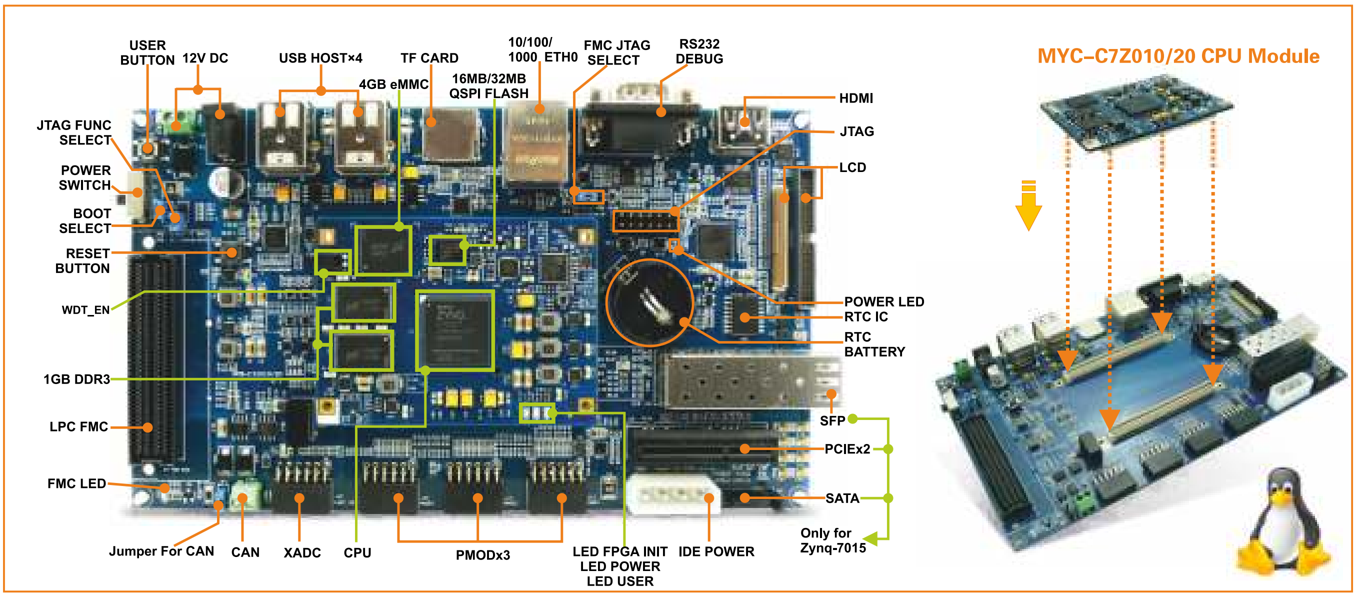
- Optimized for quick application prototyping with Zynq Ultrascale+ MPSoC
- DDR4 SODIMM – 4GB 64-bit w/ ECC attached to Processor Subsystem (PS)
- DDR4 Component – 512MB 16-bit attached to Programmable Logic (PL)
- PCIe Root Port Gen2x4, USB3, Display Port & SATA
- 4x SFP+ cages for Ethernet
- 2x FPGA Mezzanine Card (FMC) interfaces for I/O expansion including 16 x 16.3 Gb/s GTH transceivers and 64 user defined differential I/O signals

This is just one example of our wide variety of Boards and Kits from Xilinx. Please have a look in our online shop for a wider selection or ask for a quote at sales@trenz.biz.

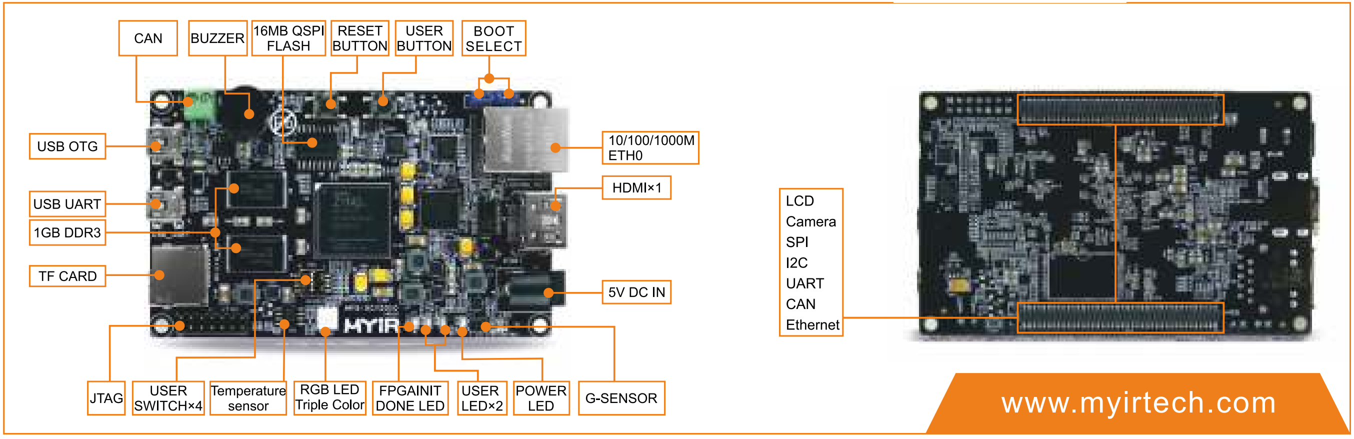
MYIR Tech Limited is a global provider of ARM hardware and software tools, design solutions for embedded applications.

MYIR is an ARM Connected Community Member and work closely with ARM and many semiconductor vendors. They sell products ranging from board level products such as development boards, single board computers and CPU modules to help with your evaluation, prototype, and system integration or creating your own applications. Their products are used widely in industrial control, medical devices, consumer electronic, telecommunication systems, Human Machine Interface (HMI) and more other embedded applications. MYIR has an experienced team and provides custom services based on many processors (especially ARM processors) to help customers make your idea a reality.

MYD–C7Z010/20 Development Board



Z-turn Board



These are just selected examples of a variety of FPGA boards from MYIR. Please have a look in our online shop or contact us at sales@trenz.biz to get a quote for any available MYIR product.

Ndigo Crate

With the Ndigo Crate it is possible to use up to 8 PCIe boards with a PC. The connection of the external chassis to the PC happens over PCIe 2 x16 for a full duplex bandwidth of 2x 8GByte/s.

The enclosure was specifically designed to operate multiple synchronized cronologic digitizer boards to create a high speed data acquisition system. It can also be used to house other DAQ cards, GPUs for high performance computing, storage adapters or networking equipment.

The extension is fully transparent. The operating system can't distinguish between boards in the PCIe expansion box and boards inside the PC itself. No drivers are required.

The slot covers are on the front side of the enclosure to easily see status information and plug in cables during operation.

The crate is delivered as a set with cable and PC link board.

Facts	Crate	Crate-3	Crate-5
Connection to Host	PCIe 2.0 x 16	PCIe 2.0 x 16	PCIe 2.0 x 16
Bandwidth to Host	8 GByte/s	8 GByte/s	8 GByte/s
Performace relative to 10Gbps Thunderbolt link	8x	8x	8x
PCIe3 16x slots with 8 lanes	-	2	2
PCIe3 16x slots with 4 lanes	-	3	3
PCIe2 16x slots with 4 lanes	8	-	-
PCI slots 5V, 32 Bit, 33MHz	-	-	2
PCI slots 3V, 32 Bit, 66MHz	-	2	-
Availability	now	now	now
Cable and link boards	included	included	included
Cable Length	3 meters (1m, 2m and 5m upon request)		